



Customer Information Notification

2020010111

Issue Date: 20-Mar-2020

Effective Date: 21-Mar-2020

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input checked="" type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - Data Sheet Update for correction and clarification | | | |

i.MXRT1050 Data Sheet
Rev 1.4 and Errata Rev
2.2 Updates

Description

NXP Semiconductors announces errata update to revision 2.2 and data sheet update to revision 1.4 for i.MXRT1050. The revision history included in the updated documents provides a detailed description of the changes.

Changes are summarized below.

For RT1050 Chip Errata:

- Added following errata:
 - ERR050235 :CCM: Incorrect clock setting for CAN affects UART clock gating
- Corrected the ERR050101 solution in the Table 2.

For RT1050 Data Sheet:

- Updated the description about external memory interfaces in the Section 1.1, Features
- Corrected the descriptions about JTAG_MOD in the Table 4, JTAG Controller interface summary
- Updated the Table 81, Boot through UART1 and removed the Table, Boot through UART2

4. Corrected the Figure 53, "10 x 10 mm BGA, case x package top, bottom, and side Views"
5. Corrected the Figure 54, "12 x 12 mm BGA, case x package top, bottom, and side Views"

The i.MXRT1050 errata revision 2.2 is attached to this notice, and can be found at:

https://www.nxp.com/products/processors-and-microcontrollers/arm-microcontrollers/i.mx-rt-crossover-mcus/i.mx-rt1050-crossover-processor-with-arm-cortex-m7-core:i.MX-RT1050?tab=Documentation_Tab&linkline=Errata

The i.MXRT1050 data sheet revision 1.4 is attached to this notice, and can be found at:

https://www.nxp.com/products/processors-and-microcontrollers/arm-microcontrollers/i.mx-rt-crossover-mcus/i.mx-rt1050-crossover-processor-with-arm-cortex-m7-core:i.MX-RT1050?tab=Documentation_Tab&linkline=Data-Sheet

Reason

The errata were added for additional technical clarification on some device features.

The data sheets have been updated to correct errors and / or provide additional technical clarification on some device features.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Shawn Shi
Position SYSTEMS & APPLICATIONS ENGINEER
e-mail address changhao.shi@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.